

EMPC 2023 CONFERENCE THE PLACE TO BE

Welcome to EMPC 2023 in Cambridge!

The European Microelectronics Packaging Conference (EMPC 2023) is the premier international conference for microelectronics packaging, organised by IMAPS and IEEE-EPSS.

The conference program will focus on industrial needs and trends and on academic long-term solutions. The event brings together researchers, innovators, technologists, business and marketing managers with an interest in semiconductor packaging

Abstract Submission

The content must be original (previously unpublished), non-confidential and non-commercial. Maximum abstract length: 300-500 words. Figures with appropriate captions, and references, can be included, they do not count in the word limit. More information can be found at www.empc2023.org.

DEADLINE
for abstract submission
is January 13, 2023

Organised by:

IMAPS UK

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Conference Venue

Genome Campus
Hinxton, Cambridge, CB10 1SA
England

Conference Chair:

Professor Anne Vanhoostenberghe
King's College London, UK

Technical Chair:

Steve Riches

For more information about the submission process, please contact our conference office:

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CALL FOR PAPERS

The 24th European Microelectronics & Packaging Conference and Exhibition
11-14 September 2023 Cambridge, UK

For more information, visit:

empc2023.org



EMPC 2023 – CONFERENCE TOPICS

Semiconductor Industry Trends

- Compound Semiconductors
- Semiconductors
- EV & Automotive
- High speed Communications
- AI and IoT
- Smart Systems

Packaging Technologies

- Emerging Packaging Technologies
- Assembly Processes
- Embedded Technologies
- Technologies
- System in Package
- Equipment Developments

Integration

- Single Chip and Multi-chip
- Photonics
- Power Electronics
- MEMS and Sensor
- SiP and Module System
- 5G / 6G / RF / Microwave / mmwave
- Wafer Level Packaging
- 2D and 3D Architectures

Performance and Reliability

- Reliability test development
- Lifetime Prediction
- Thermal Management
- Failure Modes (e.g. Ageing, Thermal Shock)
- Material Handling
- Cooling Systems

Design and Process Optimisation

- Process Modelling
- System Integration
- Power Density
- Electrical Characterisation
- Packaging Developments

Markets and Developments

- High Performance Computing
- Internet of Things (IoT)
- Automotive
- Aerospace and Defence
- Mobile/Comms
- Medical
- Industrial



Design and Test

- Co-Design
- Modelling and Simulation
- Test Technology
- Security
- Design for Recycling and Re-Use

Materials

- Emerging Research materials
- Emerging Devices
- Interconnects
- Sustainability
- Substrates
- High Temperature Material